PATENT APPLICATION
Docket No: 14321.83

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of		)
		)
	Yuichi Akage et al.	)
		)
Serial No.:	10/576,627	) Art Unit
		) 2873
Filed:	April 21, 2006	)
		)
Confirmation No.:	5766	)
		)
For:	ELECTRODE PAD ON CONDUCTIVE SEMICONDUCTOR SUBSTRATE	)

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. § 1.97

Commissioner for Patents
PO Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please find, pursuant to 37 C.F.R. § 1.98(a)(1), the enclosed Form PTO-1449 which contains a list of all patents, publications, or other items that have come to the attention of one or more of the individuals designated in 37 C.F.R. § 1.56(c). While no representation is made that these references may be "prior art" within the meaning of that term under 35 U.S.C. §§ 102 or 103, the enclosed listed references are disclosed so as to fully comply with the duty of disclosure set forth in 37 C.F.R. § 1.56.

Moreover, while no representation is made that a specific search of office files or patent office records has been conducted or that no better art exists, the undersigned attorney of record believes that the enclosed art is the closest to the claimed invention (taken in its entirety) of which the undersigned is presently aware, and no art which is closer to the claimed invention (taken in its entirety) has been knowingly withheld.

In accordance with 37 C.F.R. §§ 1.97 and 1.98, a copy of each of the listed references or relevant portion thereof that is not a US patent document is also enclosed.

Statement of Relevance of References Listed
Unaccompanied by English Translation
Under 37 CFR § 1.98(a)(3)

In accordance with 37 CFR § 1.98(a)(3), the following concise explanation of the relevance of each listed reference that is not in the English language and unaccompanied by a translation into English is provided.

Japanese Publication No. 06-013438: PURPOSE: To make it possible to provide high-speed operation, by forming an accurate terminating resistor for impedance matching when an ECL or CML circuit as a logical circuit is used. CONSTITUTION: A semiconductor chip 1 has an input-signal electrode pad 2 and a power-supply pad 4, which are put at random on a main chip face thereof. A first electrode pad 5 and a second electrode pad 7 that are connected to the electrode pads 2 and 4 are provided around the semiconductor chip 1. A chip resistor 8 for terminating resistance is adjusted to a given value so that the chip resistor 8 becomes adequate for impedance matching. Then, the chip resistor 8 provided outside is connected between the first and second electrode pads 5 and 7.

Japanese Publication No. 2003-023010: PROBLEM TO BE SOLVED: To overcome the problem that since the shape a contact section of a probing pad for high frequency with a wafer probe is restricted, mismatching of characteristic impedance occurs, leading to an increase in reflection of signals and insufficient propagation of a high-frequency signal. SOLUTION: In the probing pad for high frequency, a signal conductor 1 formed on a dielectric substrate comprises a pad section 11 which is formed with grounding conductors 2 on both sides and with which the wafer probe is to be brought into contact, a lead-out line section 13 led out from an object to be measured, a matching line section 14 provided on the pad section 11 side, and a connection line section 12 for connecting the pad section 11 and the matching line section 14. K characteristic impedance of the pad section 11 is set larger than that of the wafer probe, while a characteristic impedance of the matching line section 14 is set smaller than that of the wafer probe; and an electrical length of the connection line section 12 and the matching line section 14 combined is set 0.16 times as large as a free space wavelength of a high-frequency signal which has the maximum frequency to be adopted.

Dated this 30th day of March 2007.

Respectfully submitted,

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